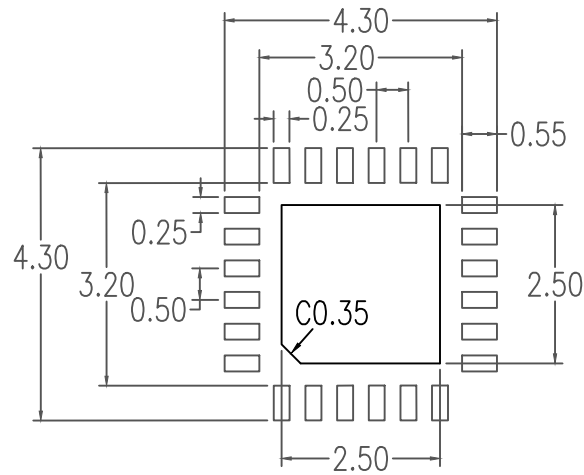


BASE ON JEDEC MO-220

DIMENSIONS IN MILIMIETER

1. DIMENSIONS
2. WEIGHT
3. PACKAGE BODY MATERIAL
4. LEAD MATERIAL
5. LEAD FINISH
6. LEAD FORM

< 0.04 g  
 LOW STRESS EPOXY  
 Cu-ALLOY  
 SOLDER PLATING  
 NO LEAD



### RECOMMENDED LAND PATTERN DIMENSION

#### NOTES:

1. ALL DIMENSIONS ARE IN MM. ANGLES IN DEGREES.
2. TOP DOWN VIEW, AS VIEWED ON PCB.
3. LAND PATTERN RECOMMENDATION PER IPC-7351B GENERIC REQUIREMENT FOR SURFACE MOUNT DESIGN AND LAND PATTERN.

Package Revision History		
Date Created	Rev No.	Description
Nov 5, 2018	Rev 02	New Format, Add Land Pattern, Change EPC Code
Jul 5, 2017	Rev 01	Update Title